Electrical Specifications

DSP56002 (5.0 Volt Operation)

DSP56L002 (3.3 Volt Operation – Lower Power Consumption)

The DSP56002 is fabricated in high density CMOS with TTL compatible inputs and outputs.

Table 5 Absolute Maximum Ratings (GND = 0 Vdc)

D. Alian	0	Value		
Rating	Symbol	DSP56002	DSP56L002	Unit
Supply Voltage	V _{CC}	-0.3 to +7.0	-0.3 to +4.0	V
All Input Voltages	V _{IN}	GND - 0.5 to V _{CC} + 0.5	GND - 0.5 to V _{CC} + 0.5	V
Current Drain per Pin Excluding V _{CC} and GND	ı	10	10	mA
Operating Temperature Range	TJ	-40 to +105	0 to +80	°C
Storage Temperature	T _{stg}	-55 to +150	-55 to +150	°C

Table 6 Thermal Characteristics of Packages

Thermal Resistance		PQFP			PGA			TQFP	
	Symbol	Value	Units	Symbol	Value	Units	Symbol	Value	Units
Junction to Ambient	Θ _{JA}	38	°C/W	Θ_{JA}	22	°C/W	Θ_{JA}	49	°C/W
Junction to Case (estimated)	Θ _{JC}	13	°C/W	ΘJC	6.5	°C/W	ΘJC	12	°C/W

Note: See discussion under "Design Considerations, Heat Dissipation," page 86.

DSP56002

DSP56002 DC Electrical Characteristics

 $(V_{CC} = 5.0 \text{ Vdc} \pm 10\%; T_J = -40^{\circ} \text{ to} +105^{\circ} \text{ C})$

Table 7 DC Electrical Characteristics for the DSP56002

Oh avas As vis Ais a	Cumbal		DSP56002		
Characteristics	Symbol	Min	Тур	Max	Units
Supply Voltage	V _{cc}	4.5	5.0	5.5	V
Input High Voltage • Except EXTAL, RESET, MODA, MODB, MODC • EXTAL • RESET • MODA, MODB, MODC	V _{IH} V _{IHC} V _{IHR} V _{IHM}	2.0 4.0 2.5 3.5	1111	V _{CC} V _{CC} V _{CC}	V V V
Input Low Voltage	V _{IL} V _{ILC} V _{ILM}	-0.5 -0.5 -0.5	- - -	0.8 0.6 2.0	V V V
EXTAL, RESET, MODA/IRQA, MODB/IRQB, MODC/NMI, BR, WT	TIN	· 			
Three-State (Off-State) Input Current (@ 2.4 V / 0.4 V)	I _{TSI}	-10	_	10	μΑ
Output High Voltage (I _{OH} = -0.4 mA)	V _{OH}	2.4	_	_	V
Output Low Voltage ($I_{OL} = 3.0 \text{ mA}$; $\overline{\text{HREQ}} I_{OL} = 6.7 \text{ mA}$, TXD $I_{OL} = 6.7 \text{ mA}$)	V _{OL}		–	0.4	٧
Internal Supply Current at 40 MHz (See Note 3) • in Wait Mode (See Note 1) • in Stop Mode (See Note 1)	l _{ccw} lccs	_	90 12 2	105 20 95	mA mA μA
Internal Supply Current at 66 MHz (See Note 3) • in Wait Mode (See Note 1) • in Stop Mode (See Note 1)	l _{cci} l _{ccw} l _{ccs}		95 15 2	130 25 95	mA mA μA
PLL Supply Current (See Note 4) at 40 MHz at 66 MHz			1 1.1	1.5 1.5	mA mA
CKOUT Supply Current (See Note 5)at 40 MHz at 66 MHz			14 28	20 35	mA mA
Input Capacitance (See Note 2)	C _{IN}	_	10	_	pF

- 1. In order to obtain these results all inputs must be terminated (i.e., not allowed to float) using CMOS levels.
- 2. Periodically sampled and not 100% tested.
- 3. **Power Consumption** in the **Design Considerations** section describes how to calculate the external supply current.
- 4. Values given are for PLL enabled.
- 5. Values given are for CKOUT enabled.

DSP56L002 DC Electrical Characteristics

 $(V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}; T_J = 0^{\circ} \text{ to } +80^{\circ} \text{ C})$

Table 8 DC Electrical Characteristics for the DSP56L002

Characteristics	Comple at		DSP56L00)2	11-11-
Characteristics	Symbol	Min	Typ Max 3.3 3.6 - V _{CC} - V _{CC} - 0.8 - 0.4 - 1	Units	
Supply Voltage	V _{CC}	3.0	3.3	3.6	V
Input High Voltage • Except EXTAL • EXTAL	V _{IH} V _{IHC}	2.0 2.7	<u>-</u>		V
Input Low Voltage • Except EXTAL • EXTAL	V _{IL}	-0.5 -0.5			V
Input Leakage Current EXTAL, RESET, MODA/IRQA, MODB/IRQB, MODC/NMI, BR, WT	I _{IN}	-1	_	1	μА
Three-State (Off-State) Input Current (@ 2.4 V / 0.4 V)	I _{TSI}	-10		10	μА
Output High Voltage (I _{OH} = -0.4 mA)	V _{OH}	2.4			٧
Output Low Voltage (I_{OL} = 3.0 mA; HREQ I_{OL} = 6.7 mA, TXD I_{OL} = 6.7 mA, WR, RD I_{OL} =2.0 mA)	V _{OL}		_	0.4	V
Internal Supply Current at 40 MHz (See Note 3) • in Wait Mode (See Note 1) • in Stop Mode (See Note 1)	I _{CCI} I _{CCW} I _{CCS}		50 10 1	65 14 50	mA mA μA
PLL Supply Current (See Note 4)		_	0.7	1.1	mA
CKOUT Supply Current (See Note 5)		_	10	14	mA
Input Capacitance (See Note 2)	C _{IN}	_	10	_	pF

- 1. In order to obtain these results all inputs must be terminated (i.e., not allowed to float) using CMOS levels.
- 2. Periodically sampled and not 100% tested.
- 3. **Power Consumption** in the **Design Considerations** section describes how to calculate the external supply current.
- 4. Values given are for PLL enabled.
- 5. Values given are for CKOUT enabled.

AC Electrical Characteristics

The timing waveforms in the AC Electrical Characteristics are tested with a V_{IL} maximum of 0.5 V and a V_{IH} minimum of 2.4 V for all pins, except EXTAL, RESET, MODA, MODB, and MODC. These four pins are tested using the input levels set forth in the DC Electrical Characteristics section. AC timing specifications which are referenced to a device input signal are measured in production with respect to the 50% point of the respective input signal's transition. DSP56002/L002 output levels are measured with the production test machine V_{OL} and V_{OH} reference levels set at 0.8 V and 2.0 V respectively.

Internal Clocks

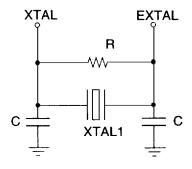
For each occurrence of T_H , T_L , T_C or I_{CYC} substitute with the expressions given in Table 9. ET_H , ET_L , and ET_C are further defined in Table 10. DF and MF are PLL division and multiplication factors set in registers.

Table 9 Internal Clocks

Characteristics	Symbol	Expression
Internal Operation Frequency	f	
Internal Clock High Period - with PLL disabled	T _H	ETH
- with PLL enabled and MF \leq 4		(Min) 0.48 x ET _C x DF/MF (Max) 0.52 x ET _C x DF/MF
- with PLL enabled and MF > 4		(Min) 0.467 x ET _C x DF/MF (Max) 0.533 x ET _C x DF/MF
Internal Clock Low Period	TL	
- with PLL disabled	_	ETL
- with PLL enabled and MF \leq 4		(Min) 0.48 x ET _C x DF/MF (Max) 0.52 x ET _C x DF/MF
- with PLL enabled and MF > 4		(Min) 0.467 x ET _C x DF/MF (Max) 0.533 x ET _C x DF/MF
Internal Clock Cycle Time	T _C	ET _C x DF/MF
Instruction Cycle Time	lcyc	2 x T _C

Clock

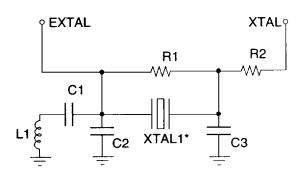
The DSP56002/L002 system clock may be derived from the on-chip crystal oscillator as shown in Figure 3, or it may be externally supplied. An externally supplied square wave voltage source should be connected to EXTAL, leaving XTAL physically unconnected (see Figure 4) to the board or socket. The rise and fall time of this external clock should be 4 ns maximum.



Fundamental Frequency Crystal Oscillator

Suggested Component Values

R = $680 \text{ K}\Omega \pm 10\%$ C = $20 \text{ pf} \pm 20\%$



3rd Overtone Crystal Oscillator

Suggested Component Values

 $R1 = 470 \text{ K}\Omega \pm 10\%$ $R2 = 330 \Omega \pm 10\%$ $C1 = 0.1 \mu\text{f} \pm 20\%$ $C2 = 26 \text{ pf} \pm 20\%$ $C3 = 20 \text{ pf} \pm 10\%$ $L1 = 2.37 \mu\text{H} \pm 10\%$

XTAL = 40 MHz, AT cut, 20 pf load, 50Ω max series resistance

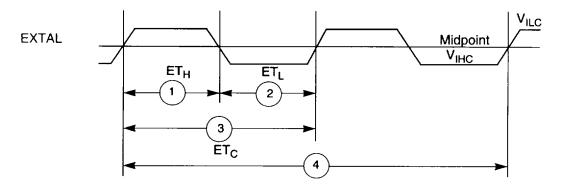
NOTES:

- The suggested crystal source is ICM, # 433163 - 4.00 (4 MHz fundamental, 20 pf load) or # 436163 - 30.00 (30 MHz fundamental, 20 pf load).
- To reduce system cost, a ceramic resonator may be used instead of the crystal. Suggested source: Murata-Erie #CST4.00MGW040

- 1. *3rd overtone crystal.
- The suggested crystal source is ICM, # 471163 - 40.00 (40 MHz 3rd overtone, 20 pf load).
- 3. R2 limits crystal current.
- Reference Benjamin Parzen, <u>The Design of Crystal and Other Harmonic Oscillators</u>, John Wiley & Sons, 1983.

Figure 3 Crystal Oscillator Circuits

Clock



NOTE: The midpoint is V_{ILC} + 0.5 (V_{IHC} - V_{ILC}).

Figure 4 External Clock Timing

Table 10 Clock Operation

Num	Characteristics	Symbol	40	MHz	66	MHz	Unit
	Characteristics	- Cymbol	Min	Max	Min	Max	Oiiit
	Frequency of Operation (EXTAL Pin)	E _f	0	40	0	66	MHz
1	Clock Input High (See Note) • with PLL disabled (46.7% - 53.3% duty cycle) • with PLL enabled (42.5% - 57.5% duty cycle)	ET _H	11.7 10.5	∞ 235.5 μs	7.09 6.36	∞ 235.5 μs	ns
2	Clock Input Low (See Note) • with PLL disabled (46.7% - 53.3% duty cycle) • with PLL enabled (42.5% - 57.5% duty cycle)	ETL	11.7 10.5	∞ 235.5 µs	7.09 6.36	∞ 235.5 μs	ns
3	Clock Cycle Time • with PLL disabled • with PLL enabled	ET _C	25 25	∞ 409.6 μs	15.15 15.15	∞ 409.6 μs	ns
4	Instruction Cycle Time = I _{CYC} = 2 × T _C (See Note) • with PLL disabled • with PLL enabled	Ісус	50 50	∞ 819.2 μs	30.3 30.3	∞ 819.2 μs	ns

NOTE: External Clock Input High and External Clock Input Low are measured at 50% of the input transition.

Phase-Locked Loop (PLL)

Table 11 Phase-Locked Loop Characteristics

Characteristics	Expression	Min	Max	Unit
VCO frequency when PLL enabled	MF x E _f (See Notes 1,2)	10	f (See Note 3)	MHz
PLL external capacitor (PCAP pin to V _{CCP})	MF × Cpcap (See Note 4) @ MF ≤ 4 @ MF > 4	MF × 340 MF × 380	MF × 480 MF × 970	pF

NOTES:

- 1. The "E" in ETH, ETL, and ETC means external.
- 2. MF is the PCTL Multiplication Factor bits (MF0 MF11). DF is the PCTL Division Factor bits (DF0 DF3).
- 3. The maximum VCO frequency is limited to the internal operation frequency.
- 4. Cpcap is the value of the PLL capacitor (connected between PCAP pin and V_{CCP}) for MF=1. The recommended value for Cpcap is 400 pF for MF ≤ 4 and 540 pF for MF > 4.

Reset, Stop, Mode Select, and Interrupt Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to} + 105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_J = 0^{\circ}$ to +80° C, $C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$

WS = Number of wait states (1 WS = T_C) programmed into external bus access using BCR (WS = 0 - 15)

Table 12 Reset, Stop, Mode Select, and Interrupt Timing

Num		40/6		
	Characteristics -	Min	Max	Unit
9	Delay from RESET Assertion to Address High Impedance (periodically sampled and not 100% tested).	_	26	ns
10	Minimum Stabilization Duration Internal Oscillator PLL Disabled (See Note 1) External clock PLL Disabled (See Note 2) External clock PLL Enabled (See Note 2)	75000 × T _C 25 × T _C 2500 × T _C	<u>-</u>	ns ns ns
11	Delay from Asynchronous RESET Deassertion to First External Address Output (Internal Reset Deassertion)	8×T _C	9×T _C +20	ns

Table continued on next page

Table 12 Reset, Stop, Mode Select, and Interrupt Timing (continued)

	Characteristics	40/66	Unit	
Num	Characteristics	Min	Max	Unit
12	Synchronous Reset Setup Time from RESET Deassertion to CKOUT transition #1	8.5	T _C	ns
13	Synchronous Reset Delay Time from the CKOUT transition #1 to the First External Address Output	8×T _C	8×T _C +6	ns
14	Mode Select Setup Time	21	_	ns
15	Mode Select Hold Time	0		ns
16	Minimum Edge-Triggered Interrupt Request Assertion Width	13	_	ns
16a	Minimum Edge-Triggered Interrupt Request Deassertion Width	13	_	ns
17	Delay from IRQA, IRQB, NMI Assertion to External Memory Access Address Out Valid Caused by First Interrupt Instruction Fetch Caused by First Interrupt Instruction Execution	5×T _C +T _H 9×T _C +T _H		ns ns
18	Delay from IRQA, IRQB, NMI Assertion to General Purpose Transfer Output Valid caused by First Interrupt Instruction Execution	11 × T _C + T _H	_	ns
19	Delay from Address Output Valid caused by First Interrupt Instruction Execute to Interrupt Request Deassertion for Level Sensitive Fast Interrupts (See Note 3)		2 T _C + T _L + (T _C × WS) - 23	ns
20	Delay from RD Assertion to Interrupt Request Deassertion for Level Sensitive Fast Interrupts (See Note 3)	_	2T _C + (T _C × WS) - 21	ns
21	Delay from WR Assertion to Interrupt Request Deassertion for Level Sensitive Fast Interrupts • WS = 0 • WS > 0 (See Note 3)	<u>-</u>	2×T _C -21 T _C +T _L + (T _C ×WS) -21	ns ns
22	Delay from General-Purpose Output Valid to Interrupt Request Deassertion for Level Sensitive Fast Interrupts - If Second Interrupt Instruction is: Single Cycle Two Cycles (See Note 3)		T _L - 31 (2 × T _C) + T _L - 31	ns ns
23	Synchronous Interrupt Setup Time from IRQA, IRQB, NMI Assertion to the CKOUT transition #2	10	T _C	ns
24	Synchronous Interrupt Delay Time from the CKOUT transition #2 to the First External Address Output Valid caused by the First Instruction Fetch after coming out of Wait State	13 × T _C + T _H	13 × T _C + T _H + 6	ns

Table 12 Reset, Stop, Mode Select, and Interrupt Timing (continued)

Num	Characteristics	40/66	l l m i d	
	Characteristics	Min	Max	Unit
25	Duration for IRQA Assertion to Recover from Stop State	12	_	ns
26	Delay from IRQA Assertion to Fetch of First Interrupt Instruction (when exiting 'Stop') • Internal Crystal Oscillator Clock, OMR bit 6 = 0 • Stable External Clock, OMR bit 6 = 1 • Stable External Clock, PCTL bit 17 = 1 (See Note 1)	65548 × T _C 20 × T _C 13 × T _C		ns ns ns
27	Duration of Level Sensitive IRQA Assertion to ensure interrupt service (when exiting 'Stop') • Internal Crystal Oscillator Clock, OMR bit 6 = 0 • Stable External Clock, OMR bit 6 = 1 • Stable External Clock, PCTL bit 17 = 1 (See Note 1)	65534 × T _C + T _L 6 × T _C + T _L 12		ns ns ns
28	Delay from Level Sensitive IRQA Assertion to Fetch of First Interrupt Instruction (when exiting 'Stop') • Internal Crystal Oscillator Clock, OMR bit 6 = 0 • Stable External Clock, OMR bit 6 = 1 • Stable External Clock, PCTL bit 17= 1 (See Note 1)	65548 × T _C 20 × T _C 13 × T _C	<u>-</u>	ns ns ns

NOTES:

- 1. A clock stabilization delay is required when using the on-chip crystal oscillator in two cases:
 - · after power-on reset, and
 - · when recovering from Stop mode.

During this stabilization period, T_C , T_H , and T_L will not be constant. Since this stabilization period varies, a delay of 75,000 \times T_C is typically allowed to assure that the oscillator is stable before executing programs.

- 2. Circuit stabilization delay is required during reset when using an external clock in two cases:
 - after power-on reset, and
 - when recovering from Stop mode.
- 3. When using fast interrupts and IRQA and IRQB are defined as level-sensitive, then timings 19 through 22 apply to prevent multiple interrupt service. To avoid these timing restrictions, the deassertive edge-triggered mode is recommended when using fast interrupt. Long interrupts are recommended when using level-sensitive mode.

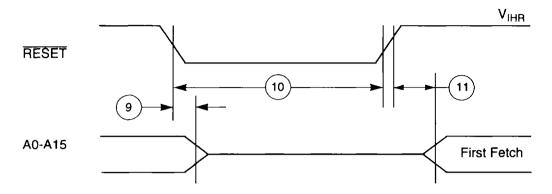


Figure 5 Reset Timing

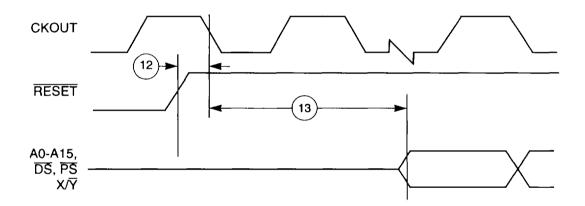


Figure 6 Synchronous Reset Timing

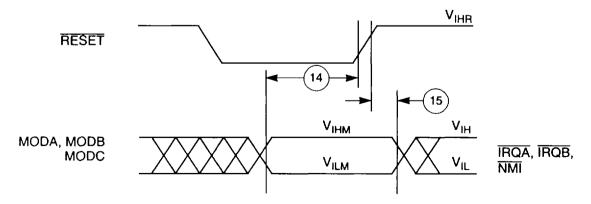


Figure 7 Operating Mode Select Timing

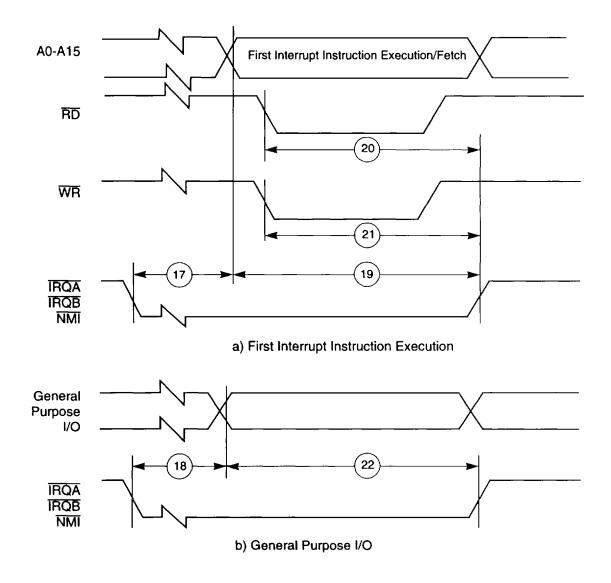


Figure 8 External Level-Sensitive Fast Interrupt Timing

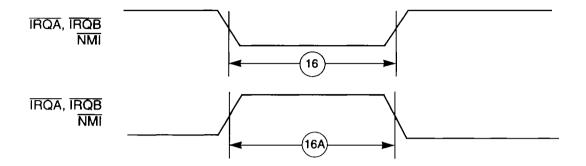


Figure 9 External Interrupt Timing (Negative Edge-Triggered)

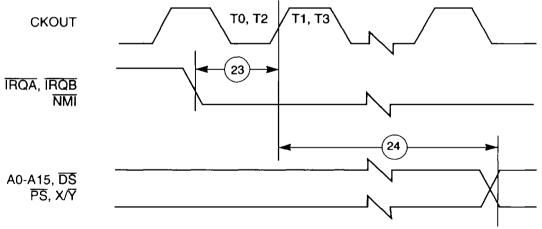


Figure 10 Synchronous Interrupt from Wait State Timing

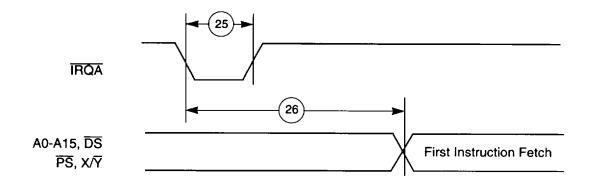


Figure 11 Recovery from Stop State Using IRQA

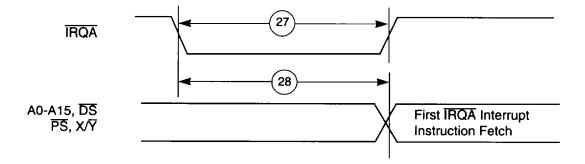


Figure 12 Recovery from Stop State Using IRQA Interrupt Service

Host I/O

Host I/O Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to } +105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_J = 0^{\circ}$ to +80° C, $C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$

Active low lines should be "pulled up" in a manner consistent with the AC and DC specifications.

Table 13 Host I/O Timing

N1	Charactariation	40/66 I	11	
Num	Characteristics	Min	Max	⊣ Unit
31	HEN/HACK Assertion Width (See Note 1) CVR, ICR, ISR, RXL Read IVR, RXH/M Read Write	T _C + 31 26 13	_ _ _	ns
32	HEN/HACK Deassertion Width (See Note 1) • Between Two TXL Writes (See Note 2) • Between Two CVR, ICR, ISR, RXL Reads (See Note 3)	13 2×T _C +31 2×T _C +31	 	ns ns ns
33	Host Data Input Setup Time Before HEN/HACK Deassertion	4		ns
34	Host Data Input Hold Time After HEN/HACK Deassertion	3	_	ns
35	HEN/HACK Assertion to Output Data Active from High Impedance	0		ns
36	HEN/HACK Assertion to Output Data Valid		26	ns
37	HEN/HACK Deassertion to Output Data High Impedance (See Note 5)	_	18	ns
38	Output Data Hold Time After HEN/HACK Deassertion (See Note 6)	2.5		ns
39	HR/W Low Setup Time Before HEN Assertion	0		ns
40	HR/W Low Hold Time After HEN Deassertion	3	-	ns
41	HR/W High Setup Time to HEN Assertion	0		ns
42	HR/W High Hold Time After HEN/HACK Deassertion	3		ns
43	HA0-HA2 Setup Time Before HEN Assertion	0		ns
44	HA0-HA2 Hold Time After HEN Deassertion	3		ns
45	DMA HACK Assertion to HREQ Deassertion (See Note 4)	3	45	ns

Table 13 Host I/O Timing (continued)

Mirana	Obawastawistia	40/66		
Num	Characteristics	Min	Max	Unit
46	DMA HACK Deassertion to HREQ Assertion (See Notes 4, 5)			
	for DMA RXL Read	$T_L + T_C + T_H$ $T_L + T_C$	_	ns
	for DMA TXL Write	T _L +T _C		ns
	all other cases	0	_	ns
47	Delay from HEN Deassertion to HREQ Assertion for RXL Read (See Notes 4, 5)	T _L +T _C +T _H	_	ns
48	Delay from HEN Deassertion to HREQ Assertion for TXL Write (See Notes 4, 5)	T _L + T _C	_	ns
49	Delay from HEN Assertion to HREQ Deassertion for RXL Read, TXL Write (See Notes 4, 5)	3	58	ns

- 1. See Host Port Considerations in the section on Design Considerations.
- 2. This timing must be adhered to only if two consecutive writes to the TXL are executed without polling TXDE or HREQ.
- 3. This timing must be adhered to only if two consecutive reads from one of these registers are executed without polling the corresponding status bits or HREQ
- 4. HREQ is pulled up by a 1 k Ω resistor.
- 5. Specifications are periodically sampled and not 100% tested.
- 6. May decrease to 0 ns for future versions.

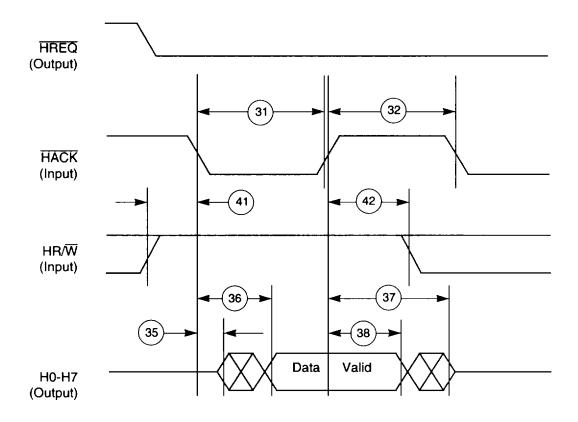


Figure 13 Host Interrupt Vector Register (IVR) Read

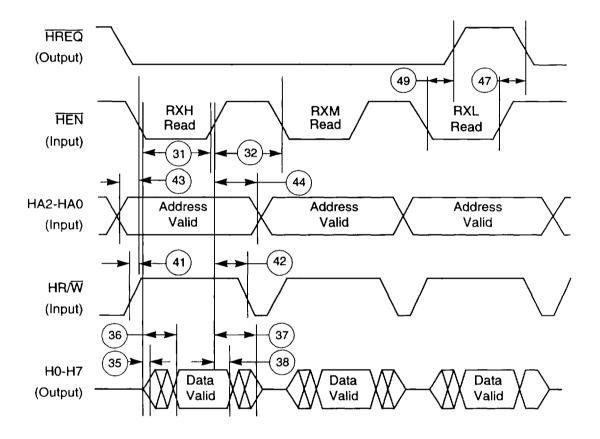


Figure 14 Host Read Cycle (Non-DMA Mode)

Host I/O

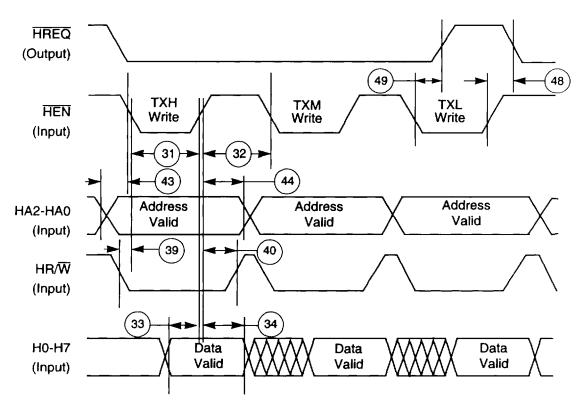


Figure 15 Host Write Cycle (Non-DMA Mode)

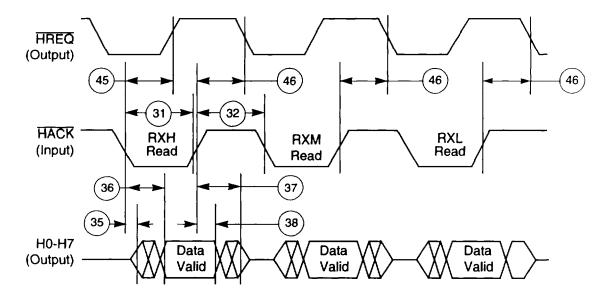


Figure 16 Host DMA Read Cycle

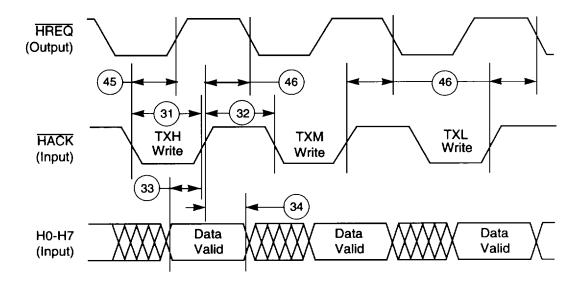


Figure 17 Host DMA Write Cycle

Serial Communication Interface (SCI) Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to} + 105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_{J} = 0^{\circ} \text{ to } +80^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

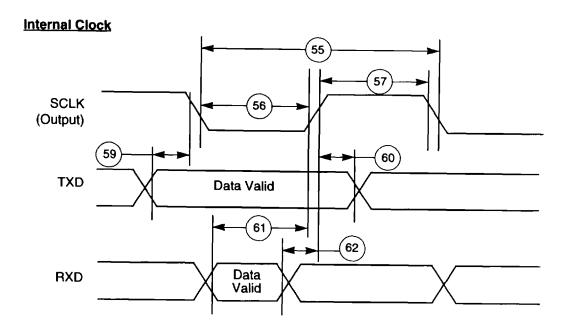
tSCC = Synchronous Clock Cycle Time (for internal clock, tSCC is determined by the SCI clock control register and T_C). The minimum tSCC value is $8 \times T_C$.

Table 14 SCI Synchronous Mode Timing

Marina	Characteristics	40/66	6 MHz	11-16
Num	Characteristics	Min	Max	Unit
55	Synchronous Clock Cycle — tSCC	8×T _C		ns
56	Clock Low Period	tSCC/2 - 10.5	_	ns
57	Clock High Period	tSCC/2 - 10.5	-	ns
58	< intentionally blank >	_	_	
59	Output Data Setup to Clock Falling Edge (Internal Clock)	tSCC/4 + T _L - 26	_	ns
60	Output Data Hold After Clock Rising Edge (Internal Clock)	tSCC/4 -T _L - 8	_	ns
61	Input Data Setup Time Before Clock Rising Edge (Internal Clock)	tSCC/4 + T _L + 23	_	ns
62	Input Data Not Valid Before Clock Rising Edge (Internal Clock)	_	tSCC/4 + T _L - 5.5	ns
63	Clock Falling Edge to Output Data Valid (External Clock)	-	32.5	ns
64	Output Data Hold After Clock Rising Edge (External Clock)	T _C + 3	_	ns
65	Input Data Setup Time Before Clock Rising Edge (External Clock)	16	-	ns
66	Input Data Hold Time After Clock Rising Edge (External Clock)	21	_	ns

Table 15 SCI Asynchronous Mode Timing — 1X Clock

	Oh a sa sharla Na	40/66		
Num	Characteristics	Min	Max	Unit
67	Asynchronous Clock Cycle - tACC	64 × T _C		ns
68	Clock Low Period	tACC/2 -11	_	ns
69	Clock High Period	tACC/2 -11		ns
70	< intentionally blank >	_		_
71	Output Data Setup to Clock Rising Edge (Internal Clock)	tACC/2 -51	_	ns
72	Output Data Hold After Clock Rising Edge (Internal Clock)	tACC/2 -51	<u>-</u>	ns



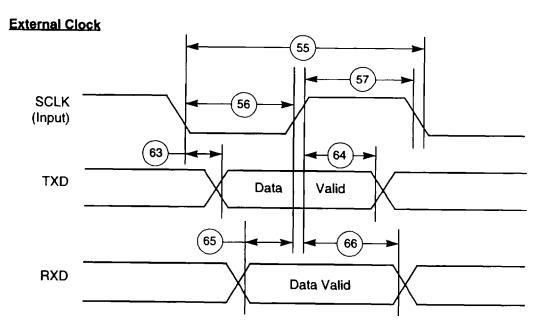
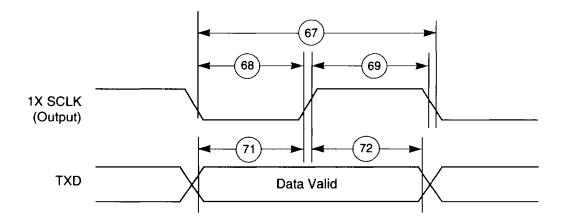


Figure 18 SCI Synchronous Mode Timing



 $\mbox{NOTE}\colon$ In the wire-OR mode, TXD can be pulled up by 1 $\mbox{K}\Omega$

Figure 19 SCI Asynchronous Mode Timing

Synchronous Serial Interface (SSI) Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{I} = -40^{\circ} \text{ to} + 105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_{J} = 0^{\circ} \text{ to } +80^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

tSSICC = SSI clock cycle time

TXC (SCK Pin) = Transmit Clock

RXC (SC0 or SCK Pin) = Receive Clock

FST (SC2 Pin) = Transmit Frame Sync

FSR (SC1 or SC2 Pin) = Receive Frame Sync

i ck = Internal Clock

x ck = External Clock

g ck = Gated Clock

i ck a = Internal Clock, Asynchronous Mode (Asynchronous implies that

STD and SRD are two different clocks)

i ck s = Internal Clock, Synchronous Mode (Synchronous implies that

STD and SRD are the same clock)

bl = bit length

wl = word length

Table 16 SSI Timing

Num	Characteristics	40/66 M			
Num	Characteristics	Min	Max	Case	Unit
80	Clock Cycle-tSSICC (See Note 1)	4×T _C 3×T _C		i ck x ck	ns
81	Clock High Period	tSSICC/2 - 10.8 T _C + T _L	_	i ck x ck	ns
82	Clock Low Period	tSSICC/2 - 10.8 T _C + T _L	_	i ck x ck	ns
83	< intentionally blank >		_	_	_
84	RXC Rising Edge to FSR Out (bl) High		40.8 25.8	x ck i ck a	ns
85	RXC Rising Edge to FSR Out (bl) Low		35.8 25.8	x ck i ck a	ns
86	RXC Rising Edge to FSR Out (wl) High		35.8 20.8	x ck i ck a	ns

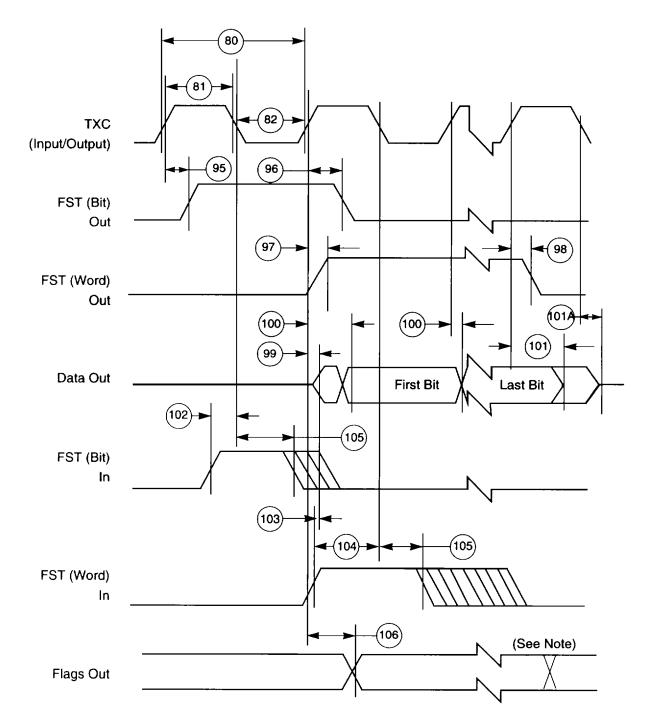
Table 16 SSI Timing (continued)

		40/6	6 MHz	0	1 Imia
Num	Characteristics	Min	Max	Case	Unit
87	RXC Rising Edge to FSR Out (wl) Low		35.8 20.8	x ck i ck a	ns
88	Data In Setup Time Before RXC (SCK in Synchronous Mode) Falling Edge	3.3 15.8 13	_ _ _	x ck i ck a i ck s	ns
89	Data In Hold Time After RXC Falling Edge	18 3.3	_	x ck i ck	ns
90	FSR Input (bl) High Before RXC Falling Edge	0.8 17.4	_	x ck i ck a	ns
91	FSR Input (wl) High Before RXC Falling Edge	3.3 18.3	_ _	x ck i ck a	ns
92	FSR Input Hold Time After RXC Falling Edge	18.3 3.3	_ _	x ck i ck	ns
93	Flags Input Setup Before RXC Falling Edge	0.8 16.7	_	x ck i ck s	ns
94	Flags Input Hold Time After RXC Falling Edge	18.3 3.3	_	x ck i ck s	ns
95	TXC Rising Edge to FST Out (bl) High	_	31.6 15.8	x ck i ck	ns
96	TXC Rising Edge to FST Out (bl) Low		33.3 18.3	x ck i ck	ns
97	TXC Rising Edge to FST Out (wl) High		30.8 18.3	x ck i ck	ns
98	TXC Rising Edge to FST Out (wl) Low		33.3 18.3	x ck i ck	ns
99	TXC Rising Edge to Data Out Enable from High Impedance	_	33.3 + T _H 20.8	x ck i ck	ns
100	TXC Rising Edge to Data Out Valid	_	33.3 + T _H 22.4	x ck i ck	ns

Table 16 SSI Timing (continued)

Maria	Oh a saada al-Al	40/6			
Num	Characteristics	Min	Max	- Case	Unit
101	TXC Rising Edge to Data Out High Impedance (See Note 2)		35.8 20.8	x ck i ck	ns
101A	TXC Falling Edge to Data Out High Impedance (See Note 2)	_	T _C +T _H	g ck	ns
102	FST Input (bl) Setup Time Before TXC Falling Edge	0.8 18.3	_	x ck i ck	ns
103	FST Input (wl) to Data Out Enable from High Impedance		30.8		ns
104	FST Input (wl) Setup Time Before TXC Falling Edge	0.8 20.0		x ck i ck	ns
105	FST Input Hold Time After TXC Falling Edge	18.3 3.3	_	x ck i ck	ns
106	Flag Output Valid After TXC Rising Edge	_	32.5 20.8	x ck i ck	ns

- 1. For internal clock, External Clock Cycle is defined by $I_{\rm cyc}$ and SSI control register. 2. Periodically sampled, and not 100% tested



NOTE: In the Network mode, output flag transitions can occur at the start of each time slot within the frame. In the Normal mode, the output flag state is asserted for the entire frame period.

Figure 20 SSI Transmitter Timing

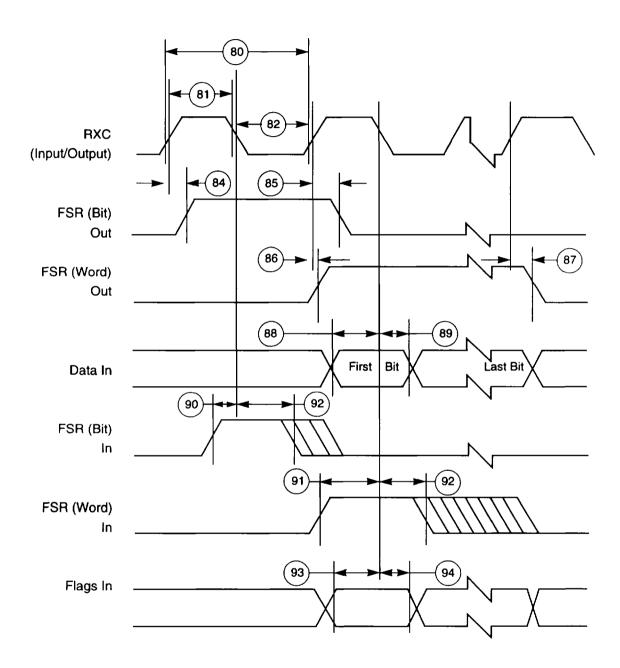


Figure 21 SSI Receiver Timing

External Bus Asynchronous

External Bus Asynchronous Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_J = -40^\circ \text{ to} + 105^\circ \text{ C}$, $C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$ DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_J = 0^\circ \text{ to} + 80^\circ \text{ C}$, $C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$

WS = Number of Wait States, as determined by BCR register (WS = 0 to 15)

Capacitance Derating

The DSP56002/L002 External Bus Timing Specifications are designed and tested at the maximum capacitive load of 50 pF, including stray capacitance. Typically, the drive capability of the External Bus pins (A0-A15, D0-D23, \overline{PS} , \overline{DS} , \overline{RD} , \overline{WR} , X/\overline{Y} , \overline{EXTP}) derates linearly at 1 ns per 12 pF of additional capacitance from 50 pF to 250 pF of loading. Port B and C pins (HI, SCI, SSI, and Timer) derate linearly at 1 ns per 5 pF of additional capacitance from 50 pF to 250 pF of loading. Active low lines should be "pulled up" in a manner consistent with the AC and DC specifications.

Table 17 External Bus Asynchronous Timing

N1	Obarratariation	40 MHz 66 MHz		66 MHz	11	
Num	Characteristics	Min	Max	Min	Max	Unit
115	Delay from BR Assertion to BG Assertion					
	With no external access from the DSP	2T _C + T _H	4T _C + T _H + 14	2T _C + T _H	4T _C + T _H + 14	ns
	During external read or write access	T _C + T _H	4T _C + T _H + (T _C × WS) + 14	T _C + T _H	4T _C + T _H + (T _C ×) WS) + 14	ns
	During external read- modify-write access During Stop mode -	T _C + T _H	6T _C + T _H + (2 × T _C × WS) +14	T _C + T _H	6T _C + T _H + (2 × T _C × WS) +14	ns
	external bus will not be released and BG will not go low	00	14	00	14	ns
	During Wait mode	T _H	T _C + T _H + 15	T _H	T _C + T _H + 15	ns
116	Delay from BR Deasser- tion to BG Deassertion	2×T _C	4×T _C + 12.5	2×T _C	4 × T _C + 12.5	ns
117	BG Deassertion Duration • During Wait mode • All other cases	T _C - 5.5 2 × T _C + T _H - 5.5	_ _	T _C - 5.5 2 × T _C + T _H - 5.5		ns ns
118	Delay from Address, Data, and Control Bus High Impedance to BG Assertion	0	_	0		ns
119	Delay from BG Deassertion to Address and Control Bus Enabled	0	T _H	0	Тн	ns

46

External Bus Asynchronous

Table 17 External Bus Asynchronous Timing (continued)

	Oh ava shartatta	40 MH		6	66 MHz	
Num	Characteristics	Min	Max	Min	Max	Unit
120	Address Valid to WR Assertion • WS = 0 • WS > 0	T _L - 6 T _C - 6		T _L - 4.5 T _C - 4.5		ns ns
121	WR Assertion Width • WS = 0 • WS > 0	T _C - 4 WS × T _C + T _L	-	T _C - 4 WS × T _C + T _L		ns ns
122	WR Deassertion to Address Not Valid	T _H - 6	-	T _H - 4	_	ns
123	WR Assertion to Data Out Active From High Impedance • WS = 0 • WS > 0	T _H - 4 0		T _H - 4 0		ns ns
124	Data Out Hold Time from WR Deassertion (the maximum specification is periodically sampled, and not 100% tested)	T _H - 7	T _H - 2.5	T _H - 5	T _H - 1.5	ns
125	Data Out Setup Time to WR Deassertion • WS = 0 • WS > 0	T _L - 0.8 WS × T _C + T _L - 0.8	-	T _L - 0.4 WS×T _C + T _L - 0.4	<u> </u>	ns
126	RD Deassertion to Address Not Valid	T _H	_	T _H - 1	_	ns
127	Address Valid to RD Deassertion • WS = 0 • WS > 0	T _C + T _L - 6 ((WS + 1) × T _C) + T _L - 6	-	T _C + T _L - 6 ((WS + 1) × T _C) + T _L - 6		ns ns
128	Input Data Hold Time to RD Deassertion	0		0		ns
129	RD Assertion Width • WS = 0 • WS > 0	T _C - 4 ((WS + 1) × T _C) - 4	=	T _C - 4 ((WS + 1) × T _C) - 4		ns ns
130	Address Valid to Input Data Valid • WS = 0 • WS > 0	_ _	$T_C + T_L - 9.5$ ((WS+1) × T_C) + $T_L - 9.5$	_ _	T _C + T _L - 7 ((WS+1) × T _C) + T _L - 7	ns ns

External Bus Asynchronous

Table 17 External Bus Asynchronous Timing (continued)

N 1	Ohavastavlatias	40	MHz	66 MHz		11
Num	Characteristics	Min	Max	Min	Max	Unit
131	Address Valid to RD Assertion	T _L - 6		T _L - 4.5	_	ns
132	RD Assertion to Input Data Valid • WS = 0 • WS > 0	-	T _C - 7.5 ((WS+1) × T _C) - 7.5		T _C - 5.5 ((WS+1) × T _C) - 5.5	ns ns
133	WR Deassertion to RD Assertion	T _C - 7	_	T _C - 5	_	ns
134	RD Deassertion to RD Assertion	T _C - 4	_	T _C - 2.5	_	ns
135	WR Deassertion to WR Assertion • WS = 0 • WS > 0	T _C - 4 T _C + T _H - 4	_	T _C -3 T _C +T _H -3		ns ns
136	RD Deassertion to WR Assertion • WS = 0 • WS > 0	T _C - 4 T _C + T _H - 4		T _C - 2.5 T _C + T _H - 2.5		ns ns

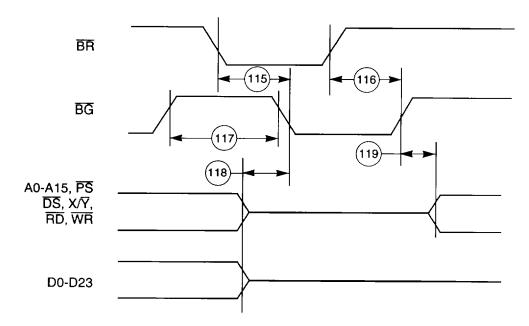


Figure 22 Bus Request / Bus Grant Timing

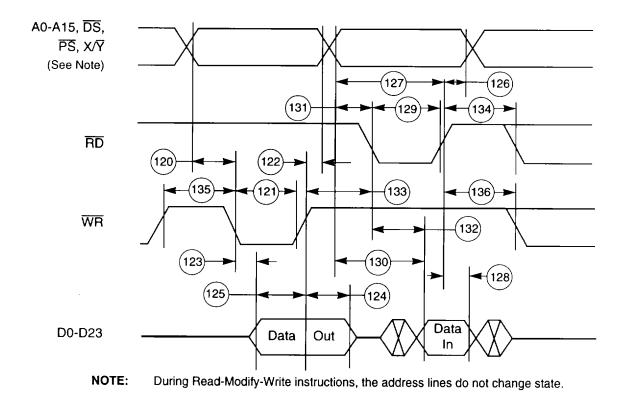


Figure 23 External Bus Asynchronous Timing

External Bus Synchronous Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to } +105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_{J} = 0^{\circ} \text{ to } +80^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

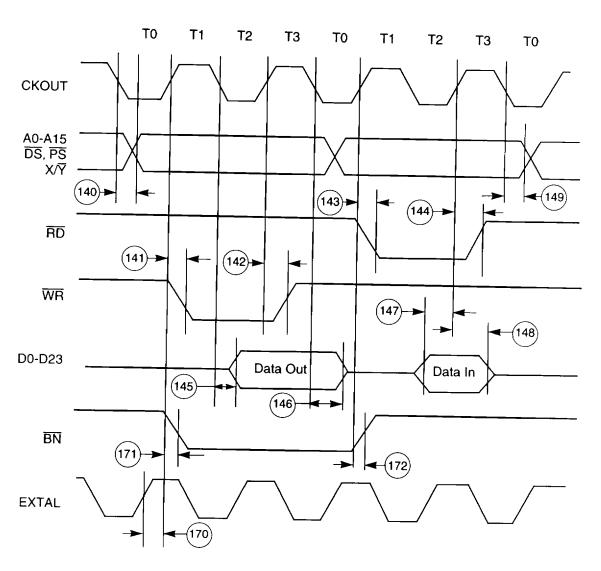
Capacitance Derating

The DSP56002/L002 external bus timing specifications are designed and tested at the maximum capacitive load of 50 pF, including stray capacitance. Typically, the drive capability of the external bus pins (A0-A15, D0-D23, \overline{PS} , \overline{DS} , \overline{RD} , \overline{WR} , X/\overline{Y} , \overline{EXTP}) derates linearly at 1 ns per 12 pF of additional capacitance from 50 pF to 250 pF of loading. Port B and C pins (HI, SCI, SSI, and Timer) derate linearly at 1 ns per 5 pF of additional capacitance from 50 pF to 250 pF of loading. Active-low lines should be "pulled up" in a manner consistent with the AC and DC specifications.

40 MHz 66 MHz Unit Num Characteristics Min Max Min Max ns CKOUT transition #1 to Address Valid 6.2 140 CKOUT transition #2 to WR Assertion 141 WS=0 4.4 กร • WS>0 $T_{H} + 4.4$ $T_H + 4$ ns (See Note 1) CKOUT transition #2 to WR Deassertion 9.1 1 5 ns 142 1.3 CKOUT transition #2 to RD Assertion 3.9 3.9 143 ns CKOUT transition #2 to RD Deassertion 3.4 -3 3 144 0 ns 4.5 CKOUT transition #1 to Data-Out Valid 145 5.4 ns CKOUT transition #1 to Data-Out Invalid 0 0 ns 146 (See Note 3) Data-In Valid to CKOUT transition #2 3.4 3.4 147 (Setup) CKOUT transition #2 to Data-In Invalid 0 0 ns 148 0 0 149 CKOUT transition #1 to Address Invalid ns (See Note 3)

Table 18 External Bus Synchronous Timing

- 1. AC timing specifications which are referenced to a device input signal are measured in production with respect to the 50% point of the respective input signal's transition.
- 2. WS are wait state values specified in the BCR.
- 3. CKOUT transition #1 to data-out invalid (specification # T146) and CKOUT transition #1 to address invalid (specification # T149) indicate the time after which data/address are no longer guaranteed to be valid.
- 4. Timings are given from CKOUT midpoint to V_{OL} or V_{OH} of the corresponding pin(s).
- 5. CKOUT transition #1 is a falling edge of CKOUT for CKP=0.



NOTE: During Read-Modify-Write Instructions, the address lines do not change states.

Figure 24 Synchronous Bus Timing

Bus Strobe / Wait

Bus Strobe / Wait Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_J = -40^{\circ} \text{ to} + 105^{\circ} \text{ C}$, $C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_{J} = 0^{\circ} \text{ to } +80^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

Table 19 Bus Strobe / Wait Timing

N1	Characteristics	40/6		
Num		Min	Max	Unit
150	CKOUT transition #1 to BS Assertion	_	5.6	ns
151	WT Assertion to CKOUT transition #1(setup time)	5.3	_	ns
152	CKOUT transition #1 to WT Deassertion for Minimum Timing	0	T _C - 7.9	ns
153	WT Deassertion to CKOUT transition #1 for Maximum Timing (2 wait states)	7.9	_	ns
154	CKOUT transition #2 to BS Deassertion	_	5.2	ns
155	BS Assertion to Address Valid	0	2.4	ns
156	BS Assertion to WT Assertion (See Note 1)	0	T _C - 10.9	ns
157	BS Assertion to WT Deassertion (See Note 1 and Note 3)	(WS-1) × T _C	WS × T _C - 13.5	ns
158	WT Deassertion to BS Deassertion	$T_{C} + T_{L} + 3.3$	$2 \times T_C + T_L + 7.8$	ns
159	Minimum BS Deassertion Width for Consecutive External Accesses	T _H - 1		ns
160	BS Deassertion to Address Invalid (See Note 2)	T _H - 4.6		ns
161	Data-In Valid to RD Deassertion (Set Up)	3.4		ns
162	BR Assertion to CKOUT transition #2 for Minimum Timing	9.5	T _C	ns
163	BR Deassertion to CKOUT transition #2 for Minimum Timing	8	T _C	ns
164	CKOUT transition #1 to BG Assertion	_	8.8	ns
165	CKOUT transition #1 to BG Deassertion	_	5.3	ns
170	EXTAL to CKOUT- PLL Disabled EXTAL to CKOUT - PLL Enabled and MF < 5 (See Note 5)	3 0.3	9.7 3.7	ns ns
171	CKOUT transition #2 to BN Assertion	_	5.7	ns
172	CKOUT transition #2 to BN Deassertion		5	ns

^{1.} If wait states are also inserted using the BCR and if the number of wait states is greater than 2, then specification numbers 156 and 157 can be increased accordingly. (Notes continued on next page)

- 2. BS deassertion to address invalid indicates the time after which the address are no longer guaranteed to be valid.
- 3. The minimum number of wait states when using BS/WT is two (2).
- 4. For read-modify-write instructions, the address lines will not change states between the read and the write cycle. However, BS will deassert before asserting again for the write cycle. If wait states are desired for each of the read and write cycle, the WT pin must be asserted once for each cycle.
- 5. When EXTAL frequency is less than 33 MHz, then timing 170 is not guaranteed for a period of $1000 \times T_C$ after PLOCK assertion following the events below:
 - when enabling the PLL operation by software.
 - when changing the multiplication factor.
 - when recovering from the stop state if the PLL was turned off and it is supposed to turn on when exiting the stop state.

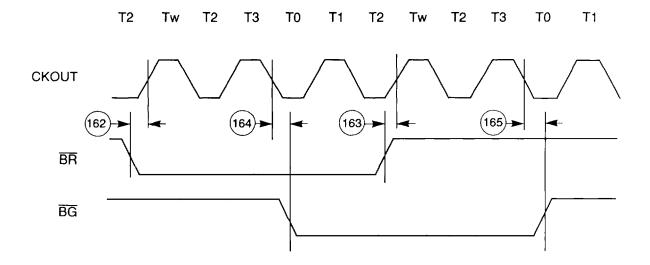
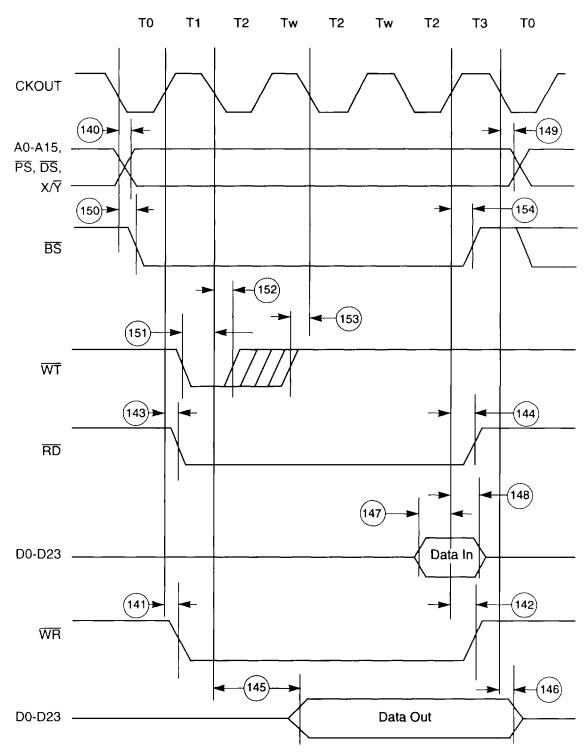


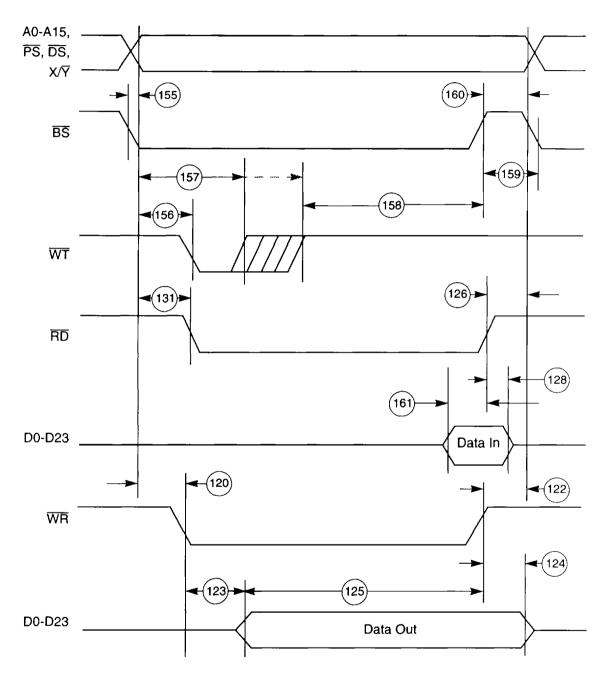
Figure 25 Synchronous Bus Request / Bus Grant Timing

Bus Strobe / Wait



NOTE: During Read-Modify-Write Instructions, the address lines do not change state. However, BS will deassert before asserting again for the write cycle.

Figure 26 Synchronous BS / WT Timings



NOTE: During Read-Modify-Write instructions, the address lines do not change state. However, BS will deassert before asserting again for the write cycle.

Figure 27 Asynchronous BS / WT Timings

OnCE™ Port Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to } +105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}, T_J = 0^{\circ} \text{ to } +80^{\circ} \text{ C}, C_L = 50 \text{ pF} + 2 \text{ TTL Loads}$

Table 20 OnCETM Port Timing

	Ohausat-ulati	40/66	41-24	
Num	Characteristics	Min	Max	Unit
230	DSCK Low	40		ns
231	DSCK High	40		ns
232	DSCK Cycle Time	200	_	ns
233	DR Asserted to DSO (ACK) Asserted	5T _C	_	ns
234	DSCK High to DSO Valid		42	ns
235	DSCK High to DSO Invalid	3	-	ns
236	DSI Valid to DSCK Low (Setup)	15		ns
237	DSCK Low to DSI Invalid (Hold)	3	_	ns
238	Last DSCK Low to OS0-OS1, ACK Active	3T _C + T _L	_	ns
239	DSO (ACK) Asserted to First DSCK High	2T _C	_	ns
240	DSO (ACK) Assertion Width	4T _C + T _H - 3	5T _C + 7	ns
241	DSO (ACK) Asserted to OS0-OS1 High Impedance (See Note 2)	~	0	ns
242	OS0-OS1 Valid to CKOUT transition #2	T _C - 21		ns
243	CKOUT transition #2 to OS0-OS1 Invalid	0	_	ns
244	Last DSCK Low of Read Register to First DSCK High of Next Command	7T _C + 10	_	ns
245	Last DSCK Low to DSO Invalid (Hold)	3	_	ns
246	DR Assertion to CKOUT transition #2 for Wake Up from WAIT State	12	Τ _C	ns
247	CKOUT transition #2 to DSO after Wake Up from Wait State	17T _C		ns
248	DR Assertion Width • to recover from Wait • to recover from Wait and enter Debug mode	15 13T _C + 15	12T _C - 15	ns
249	DR Assertion to DSO (ACK) Valid (Enter Debug Mode) After Asynchronous Recovery from Wait State	17T _C		ns

Table 20 OnCETM Port Timing (continued)

Num	Characteristics	40/66	Unit	
Num	Characteristics	Min	Max	Unit
250A	DR Assertion Width to Recover from Stop • Stable External Clock, OMR bit 6 = 0 • Stable External Clock, OMR bit 6 = 1 • Stable External Clock, PCTL bit 17= 1 (See Note 1)	15 15 15	65548T _C + T _L 20T _C + T _L 13T _C + T _L	ns
250B	DR Assertion Width to Recover from Stop and Enter Debug Mode • Stable External Clock,OMR bit 6 = 0 • Stable External Clock,OMR bit 6 = 1 • Stable External Clock,PCTL bit 17= 1 (See Note 1)	65549T _C + T _L 21T _C + T _L 14T _C + T _L	_ _ _	ns
251	DR Assertion to DSO (ACK) Valid (Enter Debug Mode) after recovery from Stop State • Stable External Clock, OMR bit 6 = 0 • Stable External Clock, OMR bit 6 = 1 • Stable External Clock, PCTL bit 17= 1 (See Note 1)	65553T _C + T _L 25T _C + T _L 18T _C + T _L	_ _ _ _	ns

NOTES:

- 1. A clock stabilization delay is required when using the on-chip crystal oscillator in two cases:
 - · after power-on reset, and
 - when recovering from Stop mode.

During this stabilization period, T_C , T_H , and T_L will not be constant. Since this stabilization period varies, a delay of $75,000 \times T_C$ is typically allowed to assure that the oscillator is stable before executing programs. While it is possible to set OMR bit 6 = 1 when using the internal crystal oscillator, it is not recommended and these specifications do not guarantee timings for that case.

2. The maximum specified is periodically sampled and not 100% tested.

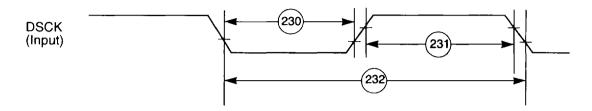


Figure 28 OnCE Serial Clock Timing

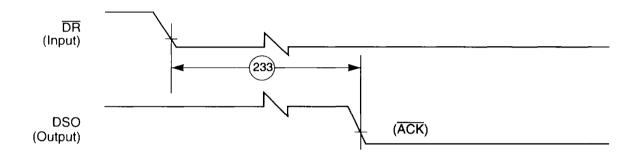
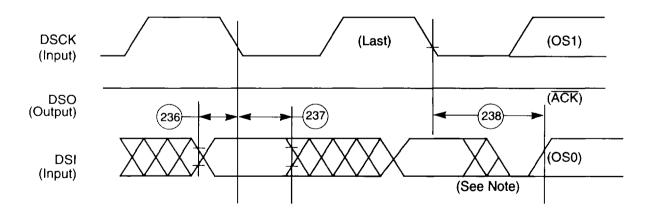


Figure 29 OnCE Acknowledge Timing



NOTE: High Impedance, external pull-down resistor

Figure 30 OnCE Data I/O To Status Timing

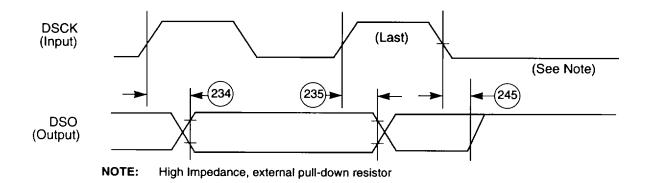


Figure 31 OnCE Read Timing

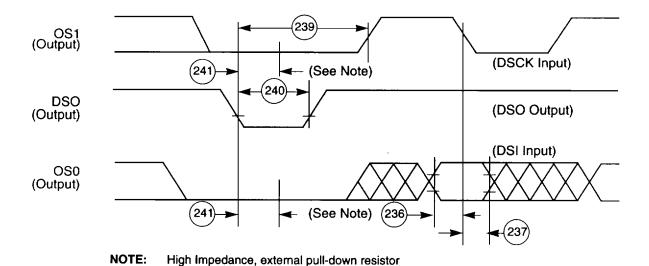
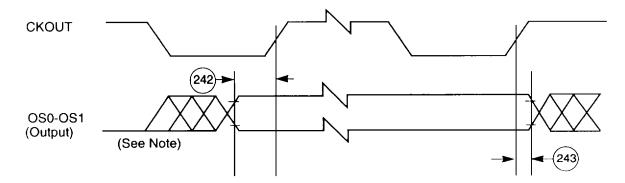


Figure 32 OnCE Data I/O To Status Timing



NOTE: High Impedance, external pull-down resistor

Figure 33 OnCE CKOUT To Status Timing

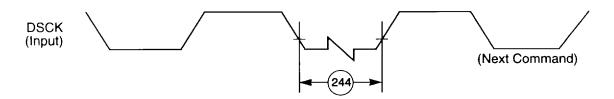


Figure 34 OnCE Read Register to Next Command Timing

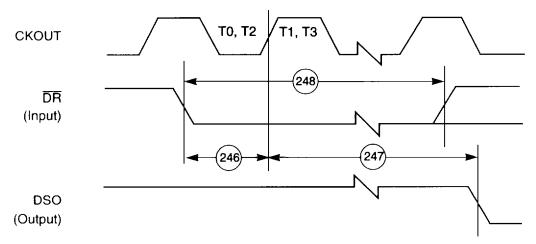


Figure 35 Synchronous Recovery from Wait State

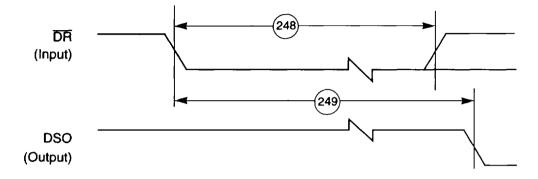


Figure 36 Asynchronous Recovery from Wait State

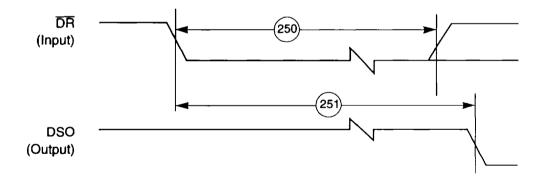


Figure 37 Asynchronous Recovery from Stop State

Timer

Timer Timing

DSP56002: $V_{CC} = 5.0 \text{ Vdc} \pm 10\%$, $T_{J} = -40^{\circ} \text{ to} + 105^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$ DSP56L002: $V_{CC} = 3.3 \text{ Vdc} \pm 0.3 \text{ V}$, $T_{J} = 0^{\circ} \text{ to} + 80^{\circ} \text{ C}$, $C_{L} = 50 \text{ pF} + 2 \text{ TTL Loads}$

NOTE: Timer functions were not available in early versions of the DSP56002/L002. See Table 30 for more information. On earlier silicon the TIO signal was an "nc" (no connection) pin.

Table 21 Timer Timing

Maria	Oh aus akaulakla a	40/66	1114	
Num	Characteristics	Min	Max	- Unit
260	TIO Low	2T _C + 7	_	ns
261	TIO High	2T _C + 7		ns
262	Synchronous Timer Setup Time from TIO (input) Assertion to CKOUT Rising Edge	10	T _C	ns
263	Synchronous Timer Delay Time from CKOUT Rising Edge to the External Memory Access Address Out Valid Caused by First Interrupt Instruction Execution	5T _C + T _H	_	ns
264	CKOUT Rising Edge to TIO (output) Assertion	0	8	ns
265	CKOUT Rising Edge to TIO (output) Deassertion	0	8	ns
266	CKOUT Rising Edge to TIO (General Purpose Output)	0	8	ns

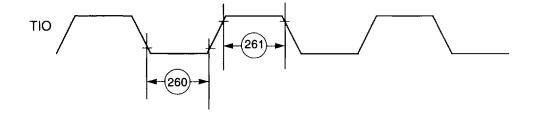


Figure 38 TIO Timer Event Input

Timer

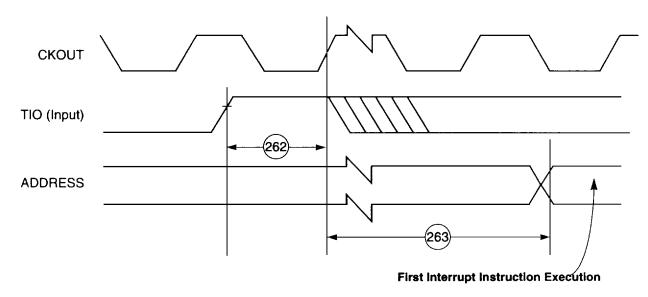


Figure 39 Timer Interrupt Generation

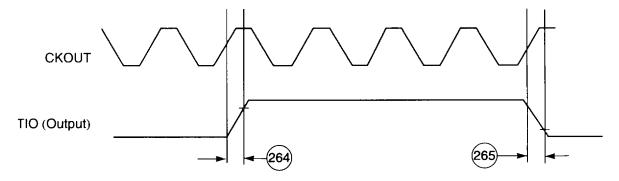


Figure 40 External Pulse Generation

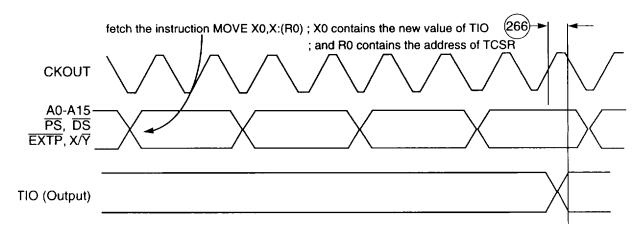


Figure 41 GPIO Output Timing